

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-293958

(43)Date of publication of application : 11.11.1997

(51)Int.Cl.

H05K 3/34

(21)Application number : 08-129266

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(22)Date of filing : 26.04.1996

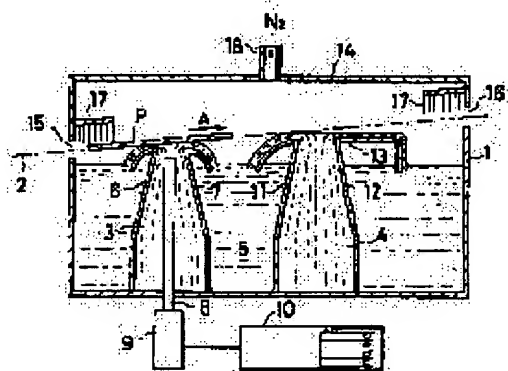
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(54) SOLDERING METHOD AND DEVICE OF PRINTED BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide the method and device capable of soldering in ultrasonic oscillation pertinent to a printed substrate meeting any requirements.

SOLUTION: A primary nozzle 3 jetting fierce waves is provided with a ultrasonic horn to be connected to a ultrasonic oscillator. A jet solder vessel 1 is provided with a cover 14 equipped with an inert gas feeding port 18 so that the inside of the cover 14 may be made inert atmospheric thereby enabling excellent soldering step causing no oxidation at all to be performed.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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